

# Complementary Darlington Power Transistor

DPAK For Surface Mount Applications

## MJD128T4G (PNP)

Designed for general purpose amplifier and low speed switching applications.

### Features

- Monolithic Construction With Built-in Base-Emitter Shunt Resistors
- High DC Current Gain:  $h_{FE} = 2500$  (Typ) @  $I_C = 4.0$  Adc
- Epoxy Meets UL 94 V-0 @ 0.125 in.
- ESD Ratings:
  - Human Body Model,  $3B > 8000$  V
  - Machine Model,  $C > 400$  V
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices\*

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	120	Vdc
Collector-Base Voltage	$V_{CB}$	120	Vdc
Emitter-Base Voltage	$V_{EB}$	5	Vdc
Collector Current Continuous Peak	$I_C$	8 16	Adc
Base Current	$I_B$	120	mAadc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	20 0.16	W W/ $^\circ\text{C}$
Total Power Dissipation* @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	1.75 0.014	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6.25	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	71.4	$^\circ\text{C}/\text{W}$

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

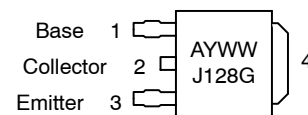
\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SILICON  
POWER TRANSISTOR  
8 AMPERES  
120 VOLTS, 20 WATTS



DPAK  
CASE 369C  
STYLE 1

### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
WW = Work Week  
J128 = Device Code  
G = Pb-Free Package

### ORDERING INFORMATION

Device	Package	Shipping†
MJD128T4G	DPAK (Pb-Free)	2,500/Tape & Reel
NJVMJD128T4G	DPAK (Pb-Free)	2,500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](http://BRD8011/D).

# MJD128T4G (PNP)

## ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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### OFF CHARACTERISTICS

Collector-Emitter Sustaining Voltage ( $I_C = 30\text{ mA}$ , $I_B = 0$ )	$V_{CE(sus)}$	120	–	Vdc
Collector Cutoff Current ( $V_{CE} = 120\text{ Vdc}$ , $I_B = 0$ )	$I_{CEO}$	–	5	mA
Collector Cutoff Current ( $V_{CB} = 100\text{ Vdc}$ , $I_E = 0$ )	$I_{CBO}$	–	10	$\mu\text{A}$
Emitter Cutoff Current ( $V_{BE} = 5\text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	–	2	mA

### ON CHARACTERISTICS

DC Current Gain ( $I_C = 4\text{ A}$ , $V_{CE} = 4\text{ Vdc}$ ) ( $I_C = 8\text{ A}$ , $V_{CE} = 4\text{ Vdc}$ )	$h_{FE}$	1000 100	12,000 –	–
Collector-Emitter Saturation Voltage ( $I_C = 4\text{ A}$ , $I_B = 16\text{ mA}$ ) ( $I_C = 8\text{ A}$ , $I_B = 80\text{ mA}$ )	$V_{CE(sat)}$	– –	2 4	Vdc
Base-Emitter Saturation Voltage (1) ( $I_C = 8\text{ A}$ , $I_B = 80\text{ mA}$ )	$V_{BE(sat)}$	–	4.5	Vdc
Base-Emitter On Voltage ( $I_C = 4\text{ A}$ , $V_{CE} = 4\text{ Vdc}$ )	$V_{BE(on)}$	–	2.8	Vdc

### DYNAMIC CHARACTERISTICS

Current-Gain-Bandwidth Product ( $I_C = 3\text{ A}$ , $V_{CE} = 4\text{ Vdc}$ , $f = 1\text{ MHz}$ )	$ h_{fe} $	4	–	MHz
Output Capacitance ( $V_{CB} = 10\text{ Vdc}$ , $I_E = 0$ , $f = 0.1\text{ MHz}$ )	$C_{ob}$	–	300	pF
Small-Signal Current Gain ( $I_C = 3\text{ A}$ , $V_{CE} = 4\text{ Vdc}$ , $f = 1\text{ kHz}$ )	$h_{fe}$	300	–	–

2. Pulse Test: Pulse Width  $\leq 300\text{ }\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

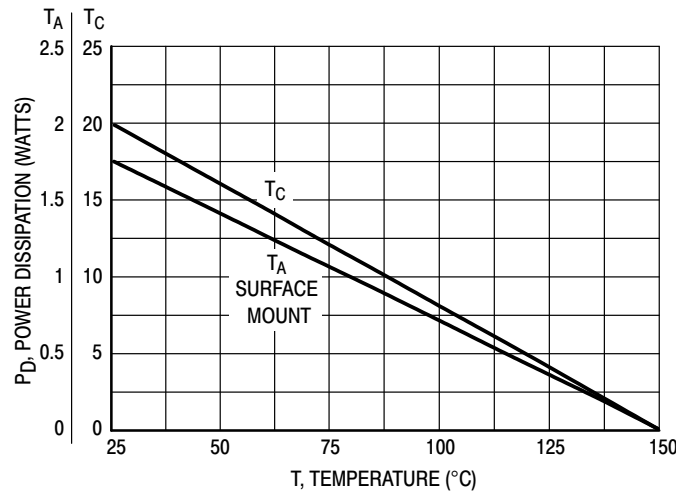


Figure 1. Power Derating

# MJD128T4G (PNP)

## TYPICAL ELECTRICAL CHARACTERISTICS

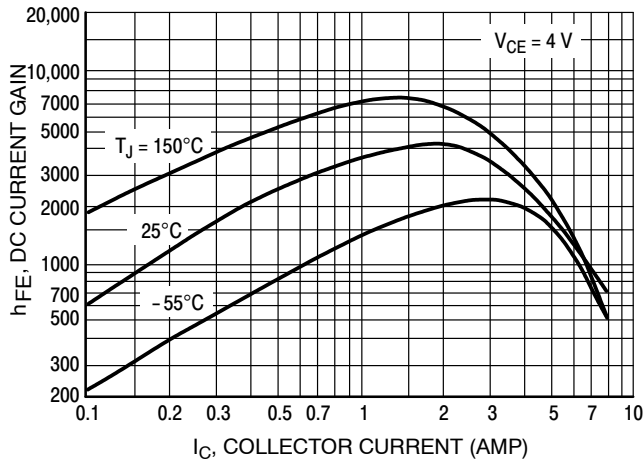


Figure 2. DC Current Gain

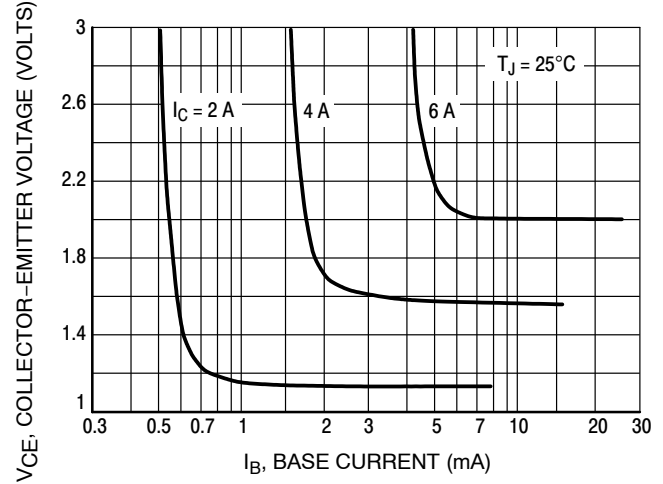


Figure 3. Collector Saturation Region

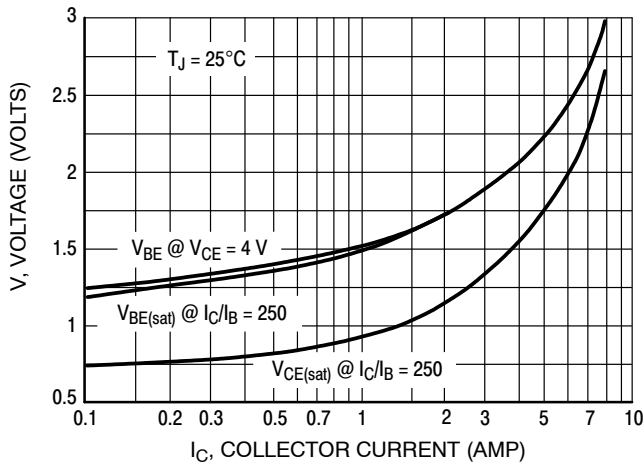


Figure 4. "On" Voltages

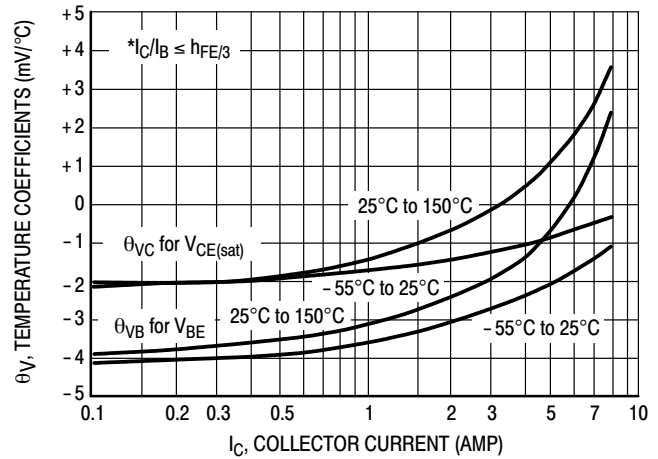


Figure 5. Temperature Coefficients

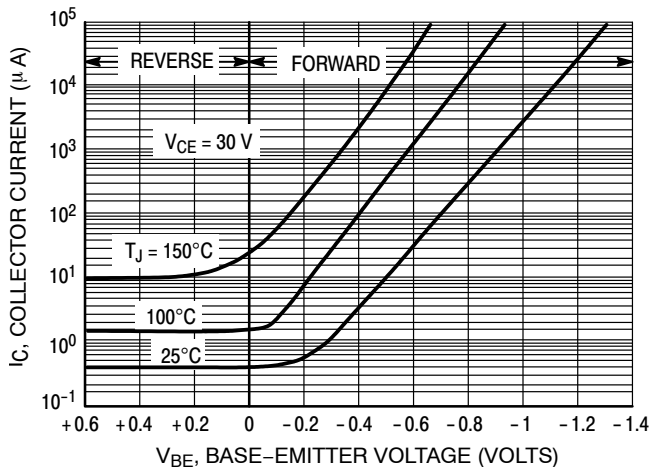


Figure 6. Collector Cut-Off Region

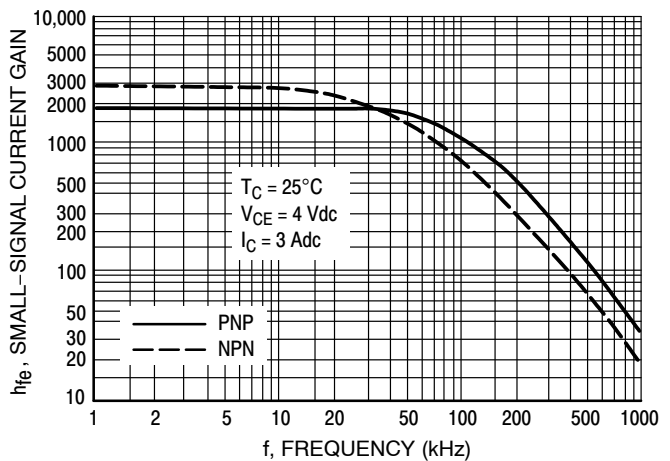


Figure 7. Small-Signal Current Gain

# MJD128T4G (PNP)

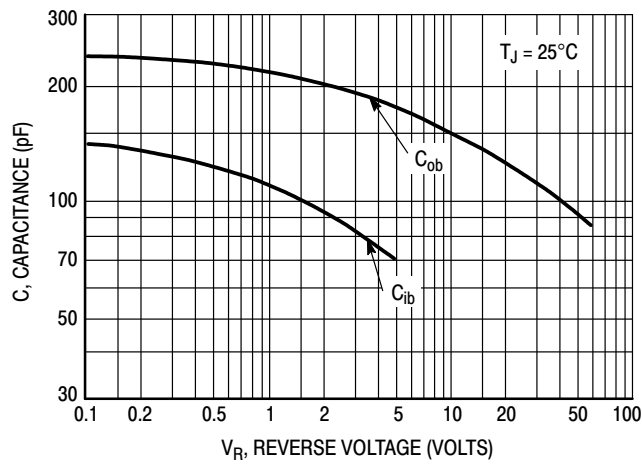


Figure 8. Capacitance

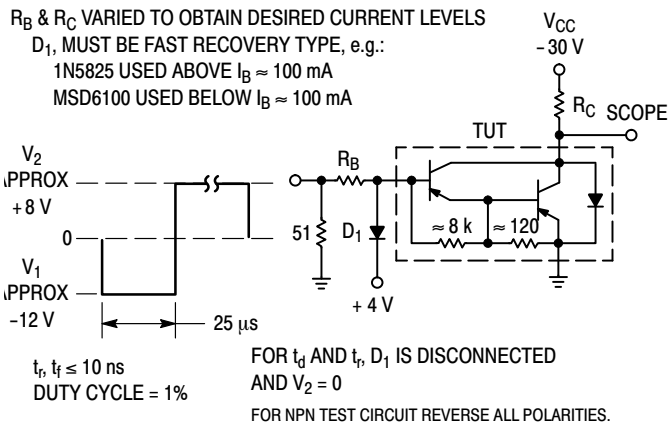


Figure 9. Switching Times Test Circuit

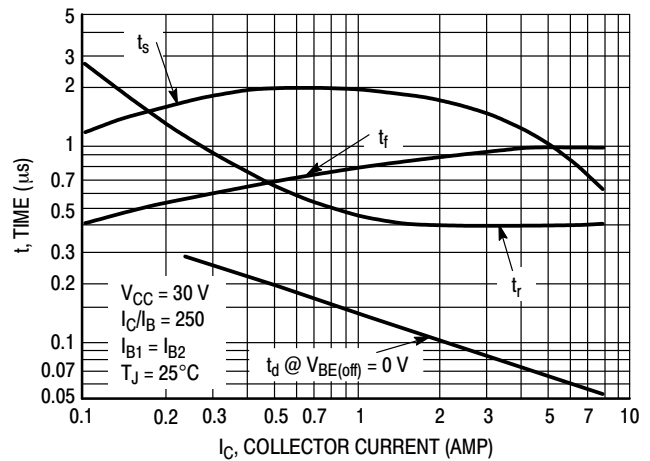


Figure 10. Switching Times

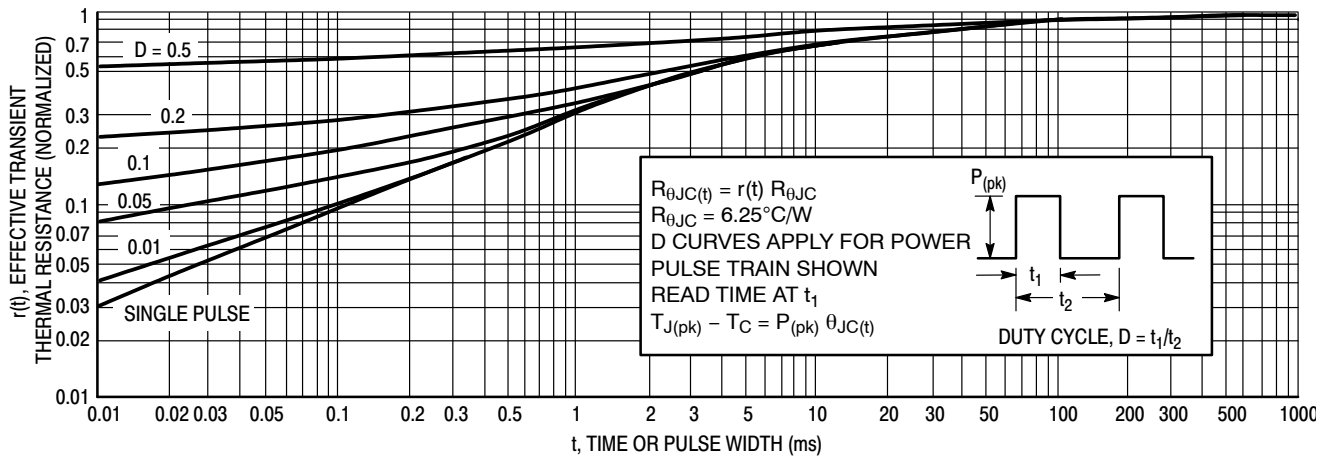
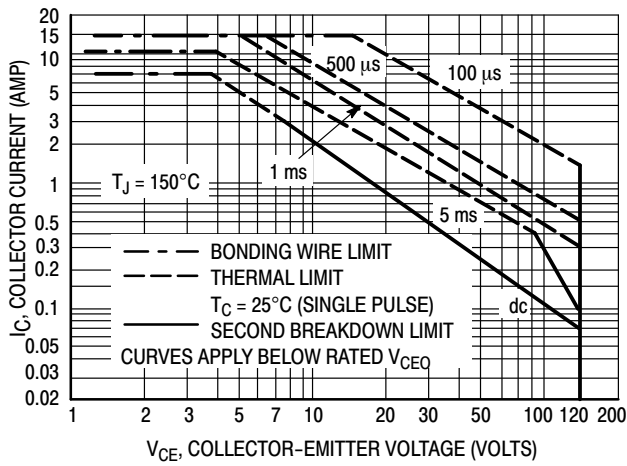


Figure 11. Thermal Response

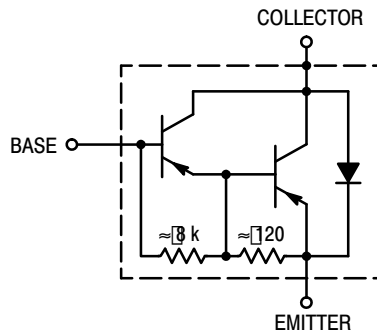
## MJD128T4G (PNP)



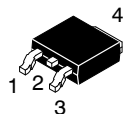
**Figure 12. Maximum Forward Bias  
Safe Operating REA**

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on  $T_{J(pk)} = 150^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} < 150^\circ\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.



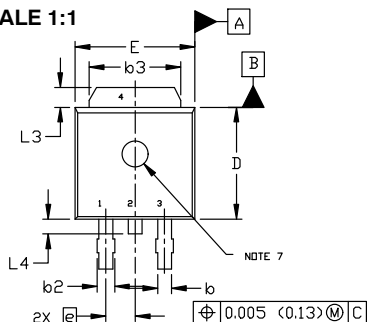
**Figure 13. Darlington Schematic**



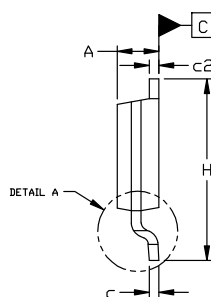
DPAK (SINGLE GAUGE)  
CASE 369C  
ISSUE G

DATE 31 MAY 2023

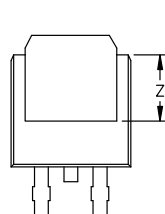
SCALE 1:1



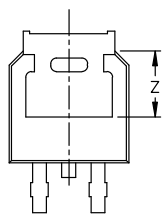
TOP VIEW



SIDE VIEW

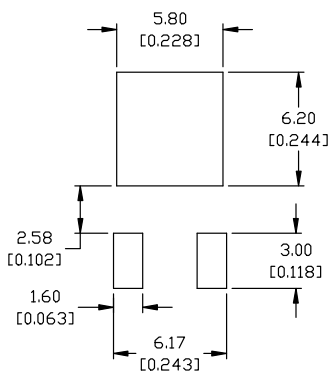


BOTTOM VIEW



BOTTOM VIEW

ALTERNATE  
CONSTRUCTIONS



RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLE 1:

PIN 1. BASE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR

STYLE 2:

PIN 1. GATE  
2. DRAIN  
3. SOURCE  
4. DRAIN

STYLE 3:

PIN 1. ANODE  
2. CATHODE  
3. ANODE  
4. CATHODE

STYLE 4:

PIN 1. CATHODE  
2. ANODE  
3. GATE  
4. ANODE

STYLE 5:

PIN 1. GATE  
2. ANODE  
3. CATHODE  
4. ANODE

STYLE 6:

PIN 1. MT1  
2. MT2  
3. GATE  
4. MT2

STYLE 7:

PIN 1. GATE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR

STYLE 8:

PIN 1. N/C  
2. CATHODE  
3. ANODE  
4. CATHODE

STYLE 9:

PIN 1. ANODE  
2. CATHODE  
3. RESISTOR ADJUST  
4. CATHODE

STYLE 10:

PIN 1. CATHODE  
2. ANODE  
3. CATHODE  
4. ANODE

NOTES:

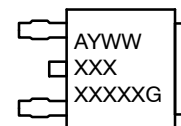
1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	----	0.040	---	1.01
Z	0.155	----	3.93	---

GENERIC  
MARKING DIAGRAM\*



IC



Discrete

XXXXXX = Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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